



HUAWEI-SPONSORED ACP'18 WORKSHOP on
“Towards the Next-Generation Optical Access:
50G-PON”

Friday, October 26st, 2018

This special Huawei-sponsored ACP'18 workshop aims to provide a platform for participants to discuss the worldwide industry effort towards the next-generation 50-Gb/s PON that is currently under standardization in both the ITU and the IEEE. This 1/2-day event will be addressing various technologies, covering innovative optical and photonic components, high-speed electronics and DSP algorithms, and system and network architectures, to enable future optical access networks to meet the challenging demands imposed by emerging services such as 4K/8K, 5G, and VR/AR. Invited speakers from leading industrial and academic institutions will be presenting and sharing their visions. This workshop will be open to all participants of ACP 2018.

Topics to be addressed include but are not limited to:

- Network operators' views on next-generation PON
- 50G-PON standardization and enabling technologies
- High speed 25G&50G optics & electrical chips and components

We look forward to the active participation of researchers, engineers, and business leaders to together contribute to the continued success of next generation PON research and development in the years to come.

Co-organizers:

Dr. Xiang Liu, Huawei Technologies, USA

Speakers:

09:00-09:20 Dechao Zhang/Lei Wang/Junwei Li China Mobile Research Institute, China

Topic: Technical requirements on 50G PON

09:20-09:40 Dezhi Zhang China Telecom, China

Topic: 50G TDM-PON: Requirement and Standardization Progress

09:40-10:00 Dr. Xiang Liu Huawei Technologies, USA

Topic: Enabling Technologies for High-Performance Low-Cost 50G-PON

10:00-10:20 Prof. Songnian Fu Huazhong University of Science & Technology, China

Topic: DSP enabled high-speed PAM-4 fiber optical transmission

10:20-10:40 Prof. Lilin Yi Shanghai Jiao Tong University, China

Topic: Machine Learning for High-Speed PONs

10:40-10:50 Coffee Break

10:50-11:10 Kangping Zhong MACOM Technology Solutions, USA

Topic: Key Technologies for Next Generation High Speed PON

11:10-11:30 Takahiko Shindo NTT Device Innovation Center, NTT Corporation, Japan

Topic: High power and high efficiency SOA integrated EML for next generation PON system

11:30-11:50 Prof. Linjuan Zhao Institute of Semiconductors, CAS, China

Topic: High speed laser for next generation PON system

11:50~12:20 Panel Discussion